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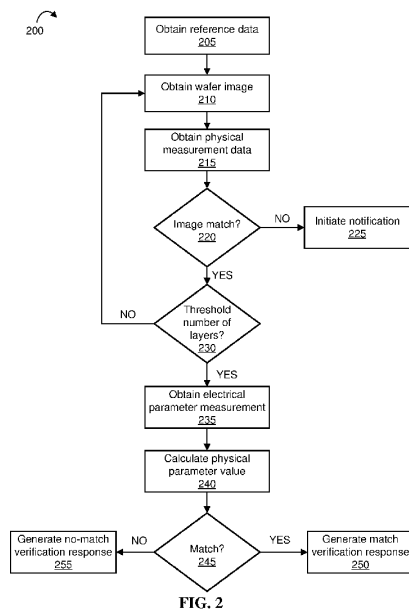
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(54) Title: **WAFER INSPECTION AND VERIFICATION**



(57) Abstract: A method includes obtaining a first reference image of a first wafer. The method includes obtaining a first image of the first wafer in a fabrication state. The first wafer has a first verification structure. The method includes obtaining, when the first wafer is in the fabrication state, a first physical measurement. The first physical measurement corresponds to the first verification structure. The method includes determining that the first image matches the first reference image. The method includes obtaining an electrical parameter measurement corresponding to a verification structure of a received wafer in a post-fabrication state. The method includes calculating a physical parameter value based on the electrical parameter measurement. The method includes generating a verification response by comparing the physical parameter value to the first physical measurement.

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